

Innovation Cooling Diamond “7 Carat” Thermal Compound Application Instructions

Cautionary Note: Due to the high amount of diamond powder (94%) in IC Diamond Compound, the material is very thick. **The plunger on the syringe should not be forced** which could result in its breaking. **Squeeze slowly using constant, even pressure** – it will take about 3-4 seconds to squeeze out the proper amount. Warming the thermal compound syringe in a cup of hot water for several minutes will enhance application.

Clean the CPU to ensure that it is clean of any grease or particulate matter. **Squeeze a pea-sized amount of IC Diamond in the center of the CPU** and apply the heatsink. Once the heatsink is mounted, the compound will spread out and cover the entire CPU and settle into a uniform thickness in about 2 hours.

Savings Note: Covering the entire CPU is a waste of compound as any excess compound is squeezed out – the final bond line is only .001 - .002 inches thick. Single line and other application methods do not provide uniform coverage and will require re-application for best results.